

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Esteban Arturo Alvarez Serrano	06/10/2008
Horman Armando Millan Sanchez	06/16/2008

RECEIVING PARTY DATA

Name:	Sony Corporation
Street Address:	1-7-1 Konan
Internal Address:	Minato-ku
City:	Tokyo
State/Country:	JAPAN
Postal Code:	108-0075

Name:	Sony Electronics Inc.
Street Address:	1 Sony Drive
City:	Park Ridge
State/Country:	NEW JERSEY
Postal Code:	07656

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12167454

CORRESPONDENCE DATA

Fax Number: (619)338-8078
Correspondence will be sent via US Mail when the fax attempt is unsuccessful.
 Phone: 619-338-8075
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 Correspondent Name: ROGITZ & ASSOCIATES
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 Address Line 2: SUITE 3120

OP \$40.00 12167454

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ATTORNEY DOCKET NUMBER:

50X9237.01

NAME OF SUBMITTER:

John L. Rogtiz

Total Attachments: 3

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RECORDATION FORM COVER SHEET
PATENTS ONLY

To the Honorable Assistant Commissioner for Patents: Please record the attached original documents or copy thereof.

1. Name(s) of conveying party:

- (1) Esteban Arturo Alvarez Serrano
- (2) Horman Armando Milfan Sanchez

2. Name and address of receiving parties:

Sony Corporation
1-7-1 Konan, Minato-ku
Tokyo, 108-0075
JAPAN

and

Sony Electronics Inc.
1 Sony Drive
Park Ridge, New Jersey 07656

3. Nature of conveyance: Assignment

Execution Dates: 1) June 10, 2008 2) June 16, 2008

4. Application number: 12/167,454 **filed** July 3, 2008 **Attorney Docket No.:** 50X9237.01

5. Name and address of party to whom correspondence concerning Assignment should be mailed:

John L. Rogitz – Customer No. 36738
Rogitz & Associates
750 B Street, Suite 3120
San Diego, CA 92101

6. Total number of applications involved: 1 **7. Total fee (37 CFR 3.41) =** \$40.00

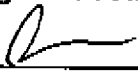
8. Credit Card Authorization

DO NOT USE THIS SPACE

9. Statement and signature:

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

John L. Rogitz
Attorney Name


Signature of Attorney

7/3/08
Date

ASSIGNMENT

WHEREAS, I, as a below named inventor, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in "SELECTIVE SOLDERING SYSTEM" for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 1-7-1 Konan, Minato-ku, Tokyo, 108-0075, Japan and Sony Electronics Inc. a Delaware corporation with offices at 1 Sony Drive, Park Ridge, New Jersey 07656 (hereinafter referenced as ASSIGNEES) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEES, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEES, as the assignees of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEES or its designee, as ASSIGNEES or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEES thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEES will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been

Docket No. 50X9237.01

or will be made or entered into which would conflict with this assignment and sale;

And I hereby authorize and request my attorney(s) of record in this application to insert the execution date, serial number and filing date of this application in the spaces that follow:

Serial Number: _____, Filing Date: _____.

This assignment is being executed on the date indicated below.



ESTEBAN ARTURO ALVAREZ SERRANO Dated: Jan/10/08



HORMAN ARMÁNDO MILLÁN SÁNCHEZ Dated: Jun/16/08